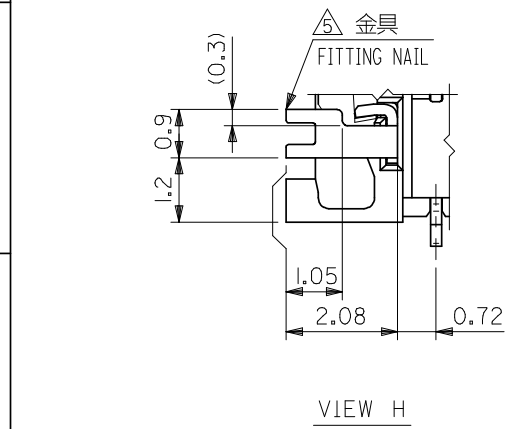
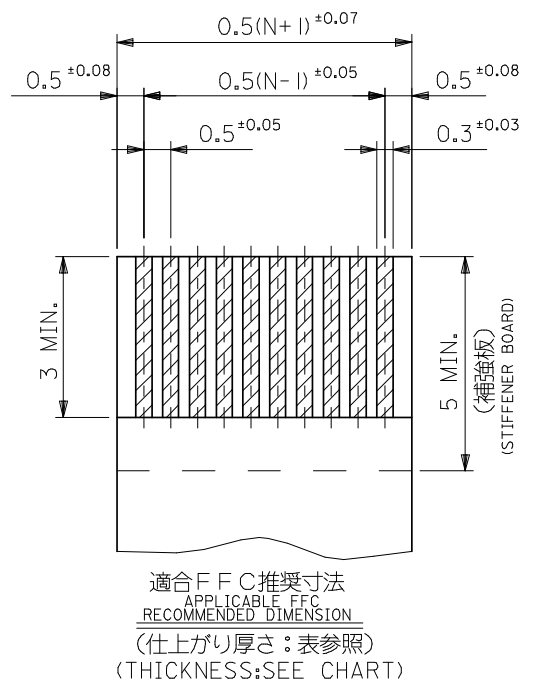
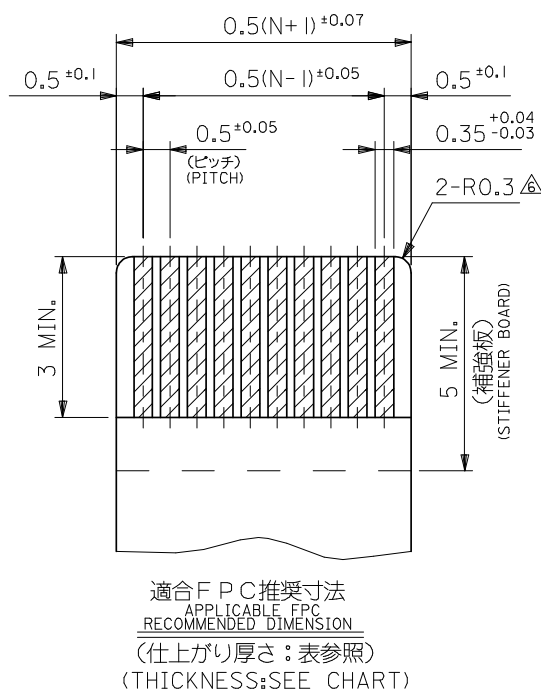
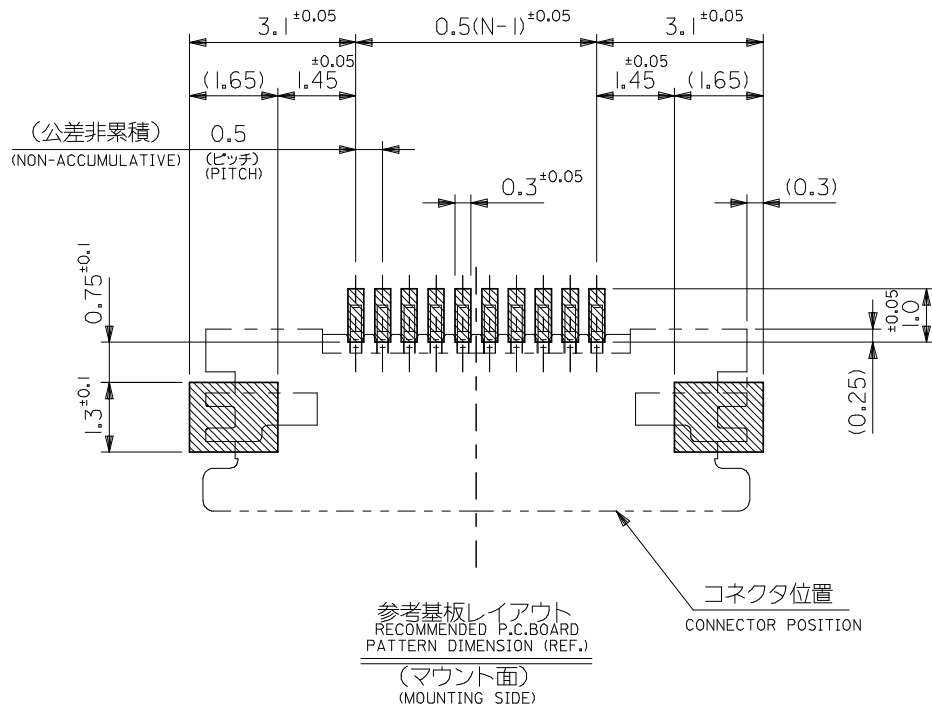


0.28 ±0.03	13.65	17	12.5	18.2	54548-2670	54548-2619	26
	12.65	16	11.5	17.2	54548-2470	54548-2419	24
	11.65	15	10.5	16.2	54548-2270	54548-2219	22
	11.15	14.5	10	15.7	54548-2170	54548-2119	21
	10.65	14	9.5	15.2	54548-2070	54548-2019	20
	10.15	13.5	9	14.7	54548-1970	54548-1919	19
	9.65	13	8.5	14.2	54548-1870	54548-1819	18
	9.15	12.5	8	13.7	54548-1770	54548-1719	17
	8.65	12	7.5	13.2	54548-1670	54548-1619	16
	8.15	11.5	7	12.7	54548-1570	54548-1519	15
	7.65	11	6.5	12.2	54548-1470	54548-1419	14
	7.15	10.5	6	11.7	54548-1370	54548-1319	13
	6.65	10	5.5	11.2	54548-1270	54548-1219	12
	6.15	9.5	5	10.7	54548-1170	54548-1119	11
5.65	9	4.5	10.2	54548-1070	54548-1019	10	
5.15	8.5	4	9.7	54548-0970	54548-0919	9	
4.65	8	3.5	9.2	54548-0870	54548-0819	8	
4.15	7.5	3	8.7	54548-0770	54548-0719	7	
3.65	7	2.5	8.2	54548-0670	54548-0619	6	
3.15	6.5	2	7.7	54548-0570	54548-0519	5	
2.65	6.0	1.5	7.2	54548-0470	54548-0419	4	
THICKNESS OF FPC	D	C	B	A	EMBOSSED TAPE ORDER No. オ-ダ-番	製品番号 MATERIAL No.	極数 CIRCUIT



REVISED EC NO: J2008-4048 DRWN:WABEI 2008/06/13 CHKD:THARYAMA 2008/06/16 APPR:NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION		
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE						
	10 OVER 30 UNDER	±0.25	Y. WADA	2004/01/09	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-						
	30 OVER	±0.3	M. SASAO	2004/01/09							
	ANGULAR ±3 °		APPROVED BY		DATE		molex		MOLEX INCORPORATED		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		M. SASAO		2004/01/09		DOCUMENT NO.		SD-54548-037			
		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						SHEET NO. 1 OF 2	



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : LCP, UL94V-0
HOUSING

アクチュエータ : PPS, UL94V-0
ACTUATOR

ターミナル : リン青銅 (t=0.2)、ニッケル下地 鍍ビスマスマッキ
TERMINAL PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING.

金具 : リン青銅 (t=0.2)、ニッケル下地 鍍メッキ
FITTING NAIL PHOSPHOR BRONZE, PURE-TIN OVER NICKEL PLATING.

2. エンボステーブ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54548-**-19 SHOULD BE LOCKED.

△ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z
に対し上方向 0 MAX.、下方向 0.15 MAX. とし

相互のバラツキ量は 0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.

△偶数極に適用。
APPLY FOR EVEN CIRCUIT.

△パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.

△R0.3はFPC導体部にかからないこと
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

7. N: 極数 N: CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

FPC について:

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。

接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC

RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT
AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN: NABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	54548-**-19	MODEL No.
	10 UNDER	±0.2	DRAWN BY Y. WADA	DATE 2004/01/09	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE 2004/01/09	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/01/09	DOCUMENT NO. SD-54548-037		
	ANGULAR ±3°		MATERIAL NO.	SEE SHEET 1	SHEET NO. 2 OF 2		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					